

TABLE OF CONTENTS

Section 1. Executive Summary	1-1
Section 2. Global IC Industry Outlook and Cycles	2-1
The Electronic System/Semiconductor Relationship	2-1
Semiconductor Content	2-3
Macroeconomics	2-6
Worldwide GDP Trends	2-6
The Aftermath of Global Recessions	2-10
Government Response to the Global Financial Crisis	2-11
Oil Price Effects	2-14
PMI Index	2-17
Worldwide Electronic System Production	2-19
The Global Semiconductor Market	2-24
Currency Effects	2-24
Semiconductor Market History and Forecast	2-25
IC Industry Cycles	2-28
Introduction	2-28
IC Market Forecast Assumptions and Database	2-32
2009 IC Industry Results	2-32
A Tale of Two Halves	2-32
A Review of the 2009 Assumptions	2-33
2010 Assumptions	2-34
2011-2014 IC Industry Forecast	2-35
The Upcoming Collision Course	2-36
2004-2014 Unit, Dollar, and ASP Analysis	2-38
IC Unit Shipments	2-40
The 2009 “V-Shaped” Recovery	2-43
Overview	2-43
IC Unit Shipments Collapse then Surge	2-44
IC Unit CAGRs	2-46
IC ASP Analysis	2-47
1Q/4Q IC Market Direction Indicator	2-51
Quarterly IC Market Growth	2-52

TABLE OF CONTENTS

Market Forecast by Region	2-54
Overview	2-54
China IC Production.....	2-60
Section 3. Leading IC Suppliers and Foundries	3-1
IC Suppliers Overview	3-1
Top Semiconductor Supplier Rankings.....	3-1
Top 50 Semiconductor Suppliers	3-1
Top 50 Fabless IC Suppliers	3-6
The Increasing Role of the Fabless IC Supplier.....	3-9
IC Foundry Industry Analysis	3-11
Pure-Play/IDM Definitions	3-11
IC Foundry Forecast Through 2014.....	3-11
2009 TSMC Rebound Example	3-14
Foundry Sales “Impact”	3-15
IC Foundry Sales Analysis	3-17
IC Foundry Sales by Company	3-17
GlobalFoundries Profile	3-21
Foundry Sales by Customer Type	3-23
Foundry Sales by Region	3-24
Foundry Sales by Application.....	3-26
Foundry Sales by Product Type	3-29
Foundry Revenue per Wafer	3-30
Foundry Sales by Feature Size.....	3-32
IC Foundry Capacity	3-35
Overview	3-35
Section 4. Capital Spending and Capacity	4-1
Semiconductor Industry Capital Spending Outlook.....	4-1
Overview	4-1
Survey versus Actual Spending Results.....	4-3
Major Semiconductor Industry Capital Spenders	4-5
Capital Spending by Nationality	4-11
Spending as a Percent of Sales.....	4-14
Capital Spending by Product Type	4-16
Recent DRAM Market History Lesson.....	4-16
Capital Spending Effectiveness.....	4-20
Capital Spending Summary.....	4-22

IC Industry Capacity Trends	4-22
Overview	4-22
IC Units Shipped per Wafer Trends.....	4-23
Total IC Industry Capacity Trends.....	4-25
Installed Capacity Leaders	4-31
2008-2010 MOS IC Capacity Forecast by Feature Size	4-33
IC Capacity by Wafer Size.....	4-36
Revenue per Wafer—When will the Rebound Occur?	4-37
Section 5. Market Overview by Device Type	5-1
Section 6. Memory Overview.....	6-1
Section 7. Flash and Non-Volatile Memory.....	7-1
Overview	7-1
Flash Memory.....	7-2
Flash Memory Market.....	7-2
Flash Memory Applications	7-7
Flash’s Growing Presence in PCs	7-9
Hybrid Flash/Hard-Disk Drives.....	7-11
Flash Memory in Cell Phones.....	7-12
Flash Memory in Handheld Computing Devices.....	7-13
Bit Growth, Weak Capex Spending to Favor IC Suppliers.....	7-15
EEPROMs	7-17
EPROMs.....	7-19
ROMs	7-20
Section 8. DRAM and SRAM	8-1
DRAM Market Review	8-1
DRAM Architectures	8-5
DRAM Bit Volume	8-7
DRAM Capital Expenditures	8-9
SRAM Market Review	8-11
Section 9. Microcomponent Overview	9-1

TABLE OF CONTENTS

Section 10. MCU and DSP	10-1
Microcontroller Market Overview	10-1
MCU Product Segments	10-8
4-/8-bit MCUs	10-8
8-bit MCU Trends	10-9
16-bit MCUs.....	10-10
32-bit MCUs.....	10-12
Digital Signal Processors.....	10-15
Section 11. MPU	11-1
Overview	11-1
Microprocessor Market	11-2
Microprocessors for Personal Computers	11-5
PC Market Forecast	11-8
Microprocessors	11-13
MPUs for Cheaper, Smaller Notebooks.....	11-24
System Chipsets	11-26
Major Changes in Chipsets.....	11-27
Graphics	11-30
Section 12. ASIC	12-1
Introduction	12-1
ASIC Market Overview.....	12-4
Introduction.....	12-4
Total ASIC Market.....	12-5
ASIC Market Forecast by Product Type	12-9
ASIC Marketshare by Region	12-14
MOS Gate Array Market	12-17
MOS Standard Cell Market.....	12-19
MOS PLD Market	12-24
Section 13. Analog	13-1
Introduction	13-1
Analog Market.....	13-1
Standard Analog Products	13-5
Amplifiers and Comparators.....	13-6
Interface Circuits.....	13-7
Voltage Regulators and References	13-7

Data Converters.....	13-9
Application-Specific Analog Products	13-10
Consumer	13-11
Computer.....	13-13
Telecom.....	13-13
Automotive.....	13-14
Industrial/Other Analog	13-14
Analog Units.....	13-16
Applications.....	13-16
Trends	13-18
Section 14. Technology	14-1
Introduction	14-1
IC Integration Trends	14-1
Transistor Count Trends.....	14-3
3D Integration	14-10
Chip Size Trends	14-15
Interconnect and Dielectric Trends	14-16
Future Interconnects	14-23
Transistor Scaling Trends.....	14-24
Device Feature Size Trends	14-24
65nm- and 45nm-Process Volumes Grow While 32nm Era Begins	14-27
Lithography Issues	14-30
Memory Cell Technologies.....	14-37
Supply Voltage and Power Trends.....	14-40
Multicore Processing	14-43
Silicon-on-Insulator (SOI)	14-44
Strained Silicon	14-48
Overcoming Scaling's Limits	14-52
High-K Gate Oxides and Metal Gates	14-53
Multiple-Gate Transistors.....	14-56
Wafer Trends	14-57
450mm Wafer Debate Continues	14-64
The Future	14-67
Section 15. Packaging	15-1
Introduction	15-1
OSAT Service Providers	15-2

TABLE OF CONTENTS

Unit Shipments by Package Type.....	15-4
General Packaging Trends.....	15-6
Package Mounting Transitions.....	15-6
Through-Silicon Vias (TSVs).....	15-11
Package Materials.....	15-11
Lead Count Trends.....	15-12
Lead Spacing Trends.....	15-15
Ball Grid Arrays.....	15-16
Chip-to-Package Interconnect Trends.....	15-16
Chip-Scale Packages.....	15-19
Stacked-Chip CSPs.....	15-23
Package-On-Package.....	15-26
Wafer-Level Packaging.....	15-29
Bare Die Assembly.....	15-31
Environmental Issues.....	15-31
Conclusion.....	15-33
Section 16. IC Economics.....	16-1
Introduction.....	16-1
Research and Development Spending.....	16-2
IC Fabrication Facility and Design Cost Trends.....	16-10
IC Cost Trends and Models.....	16-16
Die Size.....	16-17
Wafer Size.....	16-18
Total Dice Available per Wafer.....	16-20
Defect Density and Yield.....	16-20
Die Cost.....	16-24
Packaging Cost and Assembly Yield.....	16-25
Final Test Cost and Yield.....	16-26
Gross Margin and Revenue per Wafer.....	16-26
Summary.....	16-27
Section 17. Monthly Updates.....	17-1